

## SPECIFICATION FOR LCD MODULE

### MODULE NO: AFS240320TG-2.8-S000001 REVISION NO: 00

Customer's Approval:

	SIGNATURE	DATE
PREPARED BY (RD ENGINEER)	LHM	JUN-20-2011
CHECKED BY	Fr Ll	JUN-20-2011
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### **DOCUMENT REVISION HISTORY**

Version	DATE	DESCRIPTION	CHANGED BY
00	Jun-20-2011	First Issue	Lhm

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### 1. Features & Mechanical Specifications

Item	Contents LCD	Unit
LCD Type	TFT / Transmissive / Normally White	
Viewing direction	12 O'clock	
Backlight	4 Chip White LED in parallel	
Interface	8080-16bit parallel bus interface	
Driver IC	HX8347-G	
Outline Dimension	$50.0(W) \times 69.2(H) \times 2.8(T)$	mm
Glass area (W×H×T)	46.2 ×60.6 / 63.88 × 0.5	mm
Active area (W×H)	43.2 × 57.6	mm
Number of Dots	240(RGB) × 320	
Dot pitch (W×H)	0.06 × 0.18	mm
Pixel pitch (W×H)	0.18 × 0.18	mm
Operating Temperature	-20 $\sim$ +70	°C
Storage temperature	-30 $\sim$ +80	°C

### 2. Dimensional Outline

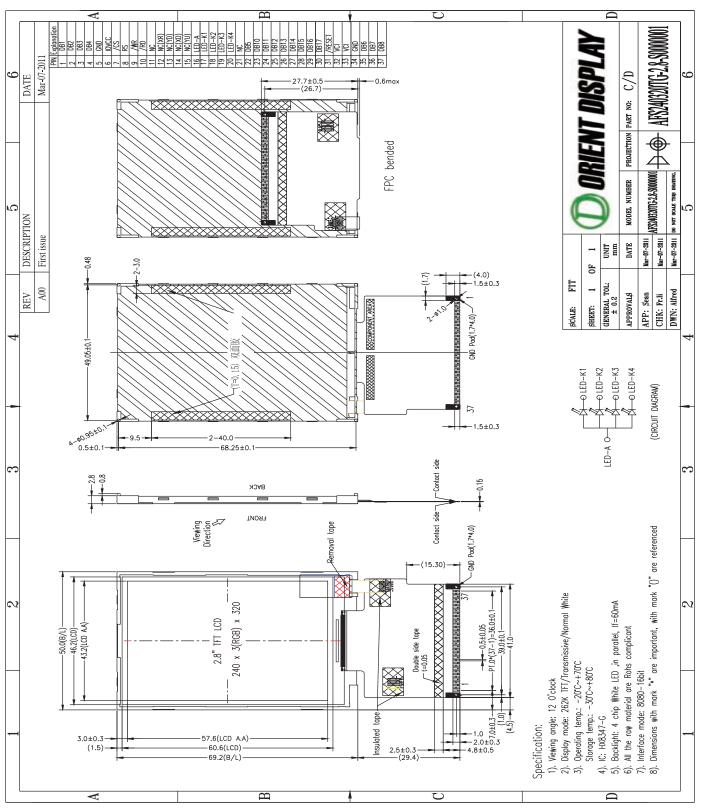


Figure 1. Dimensional outline

### 3. Block Diagram

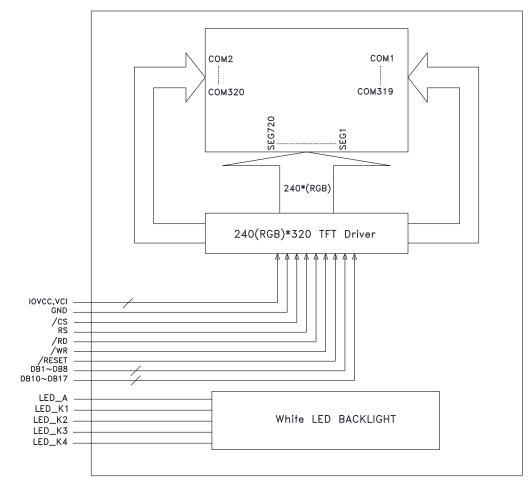


Figure 2. Block diagram

### 4. Pin Description

PIN No.	SYMBOL	Function
1~4	DB1~DB4	Data Bus
5	GND	Ground
6	IOVCC	Digital IO Pad power supply
7	/CS	Chip Select Signal ( "Low" enable)
8	RS	Display data or command selection pin RS ='1': display data or parameter. RS ='0': command.
9	/WR	Write signal.
10	/RD	Read signal.
11	NC	No Connection
12	NC(XR)	No Connection
13	NC(YD)	No Connection
14	NC(XL)	No Connection
15	NC(YU)	No Connection
16	LED_A	Backlight LED Anode
17	LED_K1	Backlight LED1 Cathode
18	LED_K2	Backlight LED2 Cathode
19	LED_K3	Backlight LED3 Cathode
20	LED_K4	Backlight LED4 Cathode
21	NC	No Connection
22	DB5	Data Bus
23~30	DB10~DB17	Data Bus
31	/RESET	Reset pin. (Active Low)
32,33	VCI	Power supply
34	GND	Ground
35~37	DB6~DB8	Data Bus

#### Interface Note:

R1	R2	Interface Mode
Open	Short	8080-8bit interface: DB17~DB10
Short	Open	8080-16bit interface: DB17~DB10, DB8~DB1 (Default Mode)
1 Unusod	ning show	uld connect to GND

1. Unused pins should connect to GND.

2. R1, R2 are SMT component on LCM FPC.

### **5. Absolute Maximum Ratings**

Item	Symbol	Rating	Unit
System Voltage range	VCI	-0.3 to +4.6	V
I/O Supply Voltage range	IOVCC	-0.3 to +4.6	V
Operating Temperature range	Тор	-20 to +70	°C
Storage Temperature range	Tst	-30 to +80	°C

### **<u>6. Electrical Characteristics</u>**

#### **DC Characteristics**

White LED  $\times$  4

Item	Symbol	Min.	Type.	Max.	Unit
System Voltage range	VCI	2.5	2.8	3.3	V
I/O Supply Voltage range	IOVCC	1.65	1.8	3.3	V

### 7. Backlight Characteristics

### (Ta = 25°C)

Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage	VF	IF = 60 mA	-	3.2	-	V
Uniformity	$\triangle Bp$	-	80	-	-	%
Luminance for LCD	Lv	IF = 60 mA	1000	-	-	cd/m <sup>2</sup>

# 8. Electro-Optical Characteristics Light Source : C-light Ta=25°C

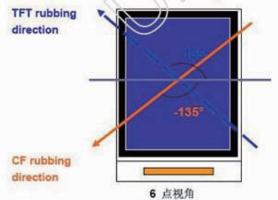
Item	1	Symbol	Condition	Min.	Тур.	Max.	Unit	Remark	
		өт		60	70	-			
View Angles		θB	CR≥10	50	60	70     -       50     -       50     -       70     -       25     30       ms     -       323     -       55     -       %	Degree	Nata 2	
View Angles		θL		60	70	5	Degree ms	Note 2	
		θR		60	70	-			
Contrast Ratio	0	CR	θ=0°	400	500	2		Note1	
Response Time		TON	25°C	88	05	20		Note1	
Response IIn	le	TOFF	250		25	30	ms %	Note4	
	White	x			0.298		1	Note5	
		У			0.354	1			
		x			0.649	(()			
Chromoticity	Red	У	Clicht		0.323	05			
Chromaticity	Croon	x	C-light		0.289	XO)		Note1	
	Green	у			0.588				
	Dhue	x	1 [	N	0.133				
	Blue	У		2	0.133	2			
NTSC			9	. (02	65	-	%	Note 5	
Transmittance	)	Т	C	NIS.	5.7	-	%	Note1	

Test Conditions:

- 1. The ambient temperature is 25°C.
- 2. The test systems refer to Note 1 and Note 2.

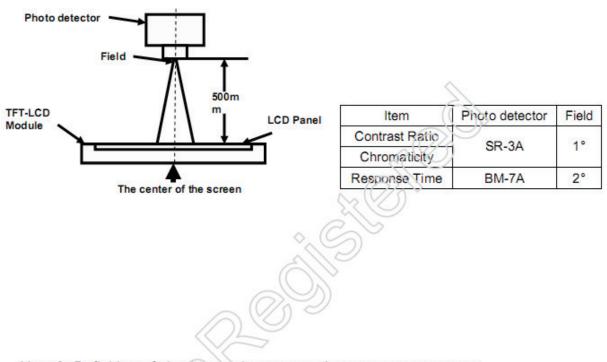
#### **Rubbing Direction** b)

- CF Substrate Rubbing direction: -135° TFT Substrate Rubbing direction 135°
  - Pi Rubbing 示意图



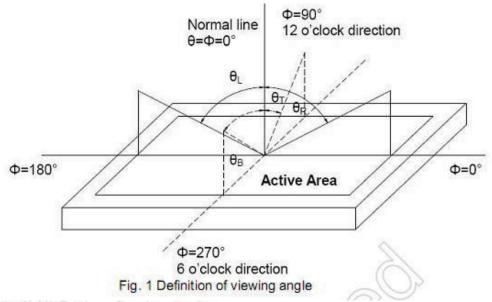
Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system, viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).

Viewing angle is measured With EWV Polarizer.



Note 3: Definition of contrast ratio

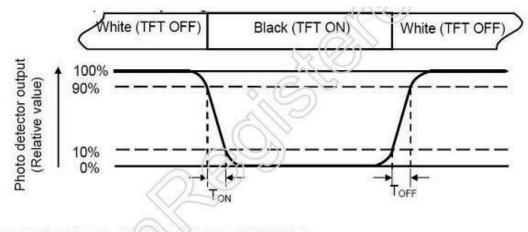
Contrast ratio (CR) = Luminance measured when LCD is on the "White" state "White state ":The state is that the LCD should driven by Vwhite.

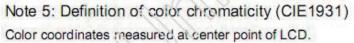
"Black state": The state is that the LCD should driven by Vblack.

Vwhite: To be determined Vblack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between "White" state and "Black" state. Rise time  $(T_{ON})$  is the time between photo detector output intensity changed from 90% to 10%. And fall time  $(T_{OFF})$  is the time between photo detector output intensity changed from 10% to 90%.





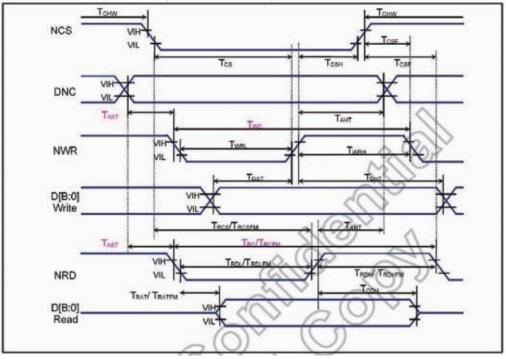
### 9. Instruction Description

(Hex)	Operation	W/R	Upper Code	Lower Code						Comme		
(HeX)	Code	WIR	D[17:8]	D7	D6	D5	D4	D3	D2	D1	DO	Commen
00	Himax ID	R		0	1	1	1	0	1	0	1	+
01	Display Mode control	W/R		DP_S TB(0)	DP_STB _S(0)			SCROL (0)	IDMON (0)	INVON (0)	PTLON (0)	-
02	Column address start 2	W/R	5 <b>4</b> 2			4	SC[15:8] (8	ъ0000_000	(00			+8
03	Column address start 1	W/R					SC[7:0] (8	b0000_000	0)			•
04	Column address end 2	W/R				1	EC[15:8] (8	ъ0000_000	00)			1
05	Column address end 1	W/R	( <b>•</b> )				EC[7:0] (8	'b1110_111	1)			•
06	Row address start 2	W/R				1	SP[15:8] (8	1000_00d	00)			+;
07	Row address start 1	W/R	•				SP[7:0] (8%	0000_0000	00)			•
08	Row address end 2	W/R	•			1	EP[15:8] (8	10000_000	01)			
09	Row address	W/R				-	EP[7:0] (8	b0011_111	1)			+:
OA	end 1 Partial area start	W/R				F	-	3'50000_00	10.011			
08	row 2 Partial area start	W/R						60000_000				
00	row 1 Partial area end	W/R		-				3'50000_00				
0D	row 2 Partial area end	W/R		-			SUS/00/09/00/0	3'50011_111	100			
0E	row 1 Vertical Scroll	W/R	1.42					3'50000_00				
OF	Top fixed area 2 Vertical Scroll	W/R						'b0000_000				
10	Top fixed area 1 Vertical Scroll	W/R				5.1.25	1	въроооо_оо				
11	height area 2 Vertical Scroll	W/R	-	-				гьо100_000				
12	height area 1 Vertical Scroll	W/R		-				3'50000_00				
0/10/	Button area 2 Vertical Scroll	00.00		-		1	State Sector	48128505 100	267			
13	Button area 1 Vertical Scroll	W/R	•			1167		гьоооо_оо				•
14	Start address 2 Vertical Scroll	W/R					100.00000.000	8'50000_00				
15	Start address 1	W/R			1.	1	/SP [7:0] (8	3.90000_00	00)	-		+)
16	Memory Access control	W/R	. • :	MY(0)	MX(0)	MV(0)	ML(0)	BGR(0)				(*).
17	COLMOD	W/R				0] (46'0110)		+	Contraction of the second s	PF[2:0] (3b'1		
18	OSC Control 2	W/R	1.00	1	PI_RADJ1	[3:0] (36'00	11)	N	P_RADJO	[3:0](4b'010	0) OSC_E	
19	OSC Control 1	W/R	().			3	*	. S#8 .			N(0)	1.5
1A	Power Control 1	W/R			•				E	BT[2:0] (001	)	1.0
1B	Power Control 2	W/R			* /		1	/RH[5:0] (0	1_1011)_4.	8V	-	*:
1C	Power Control 3	W/R	+	1. C#	+	-	14	-	1	AP[2:0] (011	)	
1D	Power Control 4	W/R	+	19	I/P	FS0[2:0](	100)	+	N/P	FS0[2:0] ](	100)	
1E	Power Control 5	W/R				FS1[2:0] ]		+		F\$1[2:0] ](		
1F	Power Control 6	W/R		GASEN(1)	VCOMG(0)		PON(0)	DK(1)	XDK(0)	DOVDH_ TRI(0)	STB(1)	
22	SRAM Write Control	W/R					SRAM W	rite		114(9)		-
23	VCOM Control 1	W/R					VMFI7:00	1000_0000	n			-
24	VCOM Control 2	W/R	-				and the part of the second second	(0010_1111				-
25	VCOM Control 3						the second se	the second se				-
25	Display Control	W/R					+	0101_0111		:0](0001)		*:
27	1 Display Control 2	W/R		PTI	:0](10)	PTVI	1:0](10)			PTG(1)	REF(1)	

(Hex)	Operation	W/R	Upper Code	LOWELCODE								
errora.	Code	min	D[17:8]	D7	D6	D5	D4	D3	D2	D1	D0	Commer
28	Display Control 3	W/R	-			GON(1)	DTE(0)	D[1:	0] (00)			
29	Frame Rate control 1	W/R			I/PI_RTM	RTN[3:0](1000) N/P_RTN[3:0](1000)						
2A	Frame Rate Control 2	W/R	-	-	20	I/PI_DIV	/[1:0](00)	2	2	N/P_DIV	[1:0](00)	125
2B	Frame Rate Control 3	W/R		10	0	N/1	P_DUM[7:0	) (8b'0001_	1100)			1.00
2C	Frame Rate Control 4	W/R				I/P	U_DUM[7:0	] (86'0001_	1100)			
2D	Cycle Control 1	W/R				0	DON[7:0]	(8'50000_1	101)			
2E	Cycle Control 2	W/R	(#)			(	3DOF[7:0]	(8'b0111_10	(00			
2F	Display inversion	W/R	-		I/PI	NW[2:0](3	b'001)		N/P_	NW[2:0] (3b	(001)	
31	RGB interface control 1	W/R		1	- 8			-	•	0.5396	:0](00)	
32	RGB interface control 2	W/R		-	-	1 A.	8	(0)	HSPL (0)	VSPL (0)	EPL (0)	+
33	RGB interface control 3	W/R		_			HE	IP[7:0]	_			
34	RGB interface control 4	W/R		HBP	[9:8]				2[5:0]			
36	Panel Characteristic	W/R		*		- 24-	94	SS_P anel	GS_Pan el	REV_P anel	BGR_P anel	(3 <b>8</b> 3)
38	OTP Control 1	W/R		OTP_P	TM[1:0]	OTP_V	ARDJ[1:0]	OTP_ POR	OTP_O TPEN	OTP_P PROG	OTP_P WE	
39	OTP Control 2	W/R	•		•	•	-	•	OTP_YA	OTP_YA1	OTP_Y A0	
3A	OTP Control 3	W/R		-	+		OTP_XA	XA3	OTP_XA 2	1.1.1	OTP_XA0	
38	OTP Control 4	R		OTPDA TA7	OTPD ATA6	OTPDA TA5	OTPDAT A4	ATA3	OTPDAT A2	A1	OTPDATA 0	
3C	CABC Control 1	W/R	•			-	DBV[7	:0](8'h00)			_	•
3D	CABC Control 2	W/R	(*)		*	BCTRL (0)	•	(0)	BL (0)	•	+	(*)
3E	CABC Control 3	W/R	1		1			•	3	C1 (0)	C0 (0)	
3F	CABC Control 4	W/R	•				CWB[/	:0](8'h00)	ner ni			
40	r1 Control (1)	W/R							0[5:0]			
41	r1 Control (2)	W/R	•	-	-				1[5:0]			
42	r1 Control (3)	W/R	•		*				2[5.0]			+
43	r1 Control (4)	W/R	-		*				3[5:0]			
44	r1 Control (5)	W/R			•				4[5:0]			+
45	r1 Control (6)	W/R							5[5:0]			
46	r1 Control (7)	W/R		*				PRP0[6:0				
47	r1 Control (8)	W/R		- 141				PRP1[6:0				+ 1
48	r1 Control (9)	W/R	*	(#)					PKP0[4:0]			
49	r1 Control (10)	W/R				.+			PKP1[4:0]			+
4A	r1 Control (11)	W/R	•	-	*				PKP2[4:0]	7		+
48	r1 Control (12)	W/R							PKP3[4:0]	2		*
4C	r1 Control (13)	W/R	•	*	•			Ver	PKP4[4:0]			•
50	r1 Control (14)	W/R	•						0[5:0]			
51	r1 Control (15)	W/R	-						1[5:0]			-
52	r1 Control (16)	W/R	•		•				2[5:0]			•
53	r1 Control (17)	W/R							3[5:0]			
54	r1 Control (18)	W/R	-	-	-				4[5:0]		X	+
55	r1 Control (19)	W/R	*						5[5:0]			
56	r1 Control (20)	W/R	•					PRN0[6:0				+
57	r1 Control (21)	W/R						PRN1[6:0	Configuration of the second second			
58	r1 Control (22)	W/R	-						0[4:0]			
59	r1 Control (23)	W/R		*					1[4:0]			
5A	r1 Control (24)	W/R	•	-	-				2[4:0]			٠
58	r1 Control (25)	W/R	•						3[4:0]			
5C	r1 Control (26)	W/R	-		-		004.00		4[4:0]			
5D	r1 Control (27)	W/R		CGMN	1[1:0]	CGMN	and the second second second second		21[1:0]	CGMP	20[1:0]	
60	TE Control	W/R	•	-	•	ID15	TE_mod e(0)	TEOE(0)	1542	-	+	
61	ID1	W/R		ID17	ID16	ID15	ID14	ID13	ID12	1D11	ID10	
62	1D2	W/R	•	1D27	1D26	ID25	1D24	ID23	1D22	ID21	ID20	•
63	1D3	W/R	:+:	ID37	1D36	ID35	ID34	ID33	ID32	ID31	ID30	11.41

(Hex)	Operation	W/R	Upper Lower Code							Comment		
1000	Code	100000000	D[17:8]	D7	D6	D5	D4	D3	D2	D1	DO	100000000
84	TE Output line2	W/R		TESEL15	TESEL14	TESEL 13	TESEL 12	TESEL11	TESEL10	TESEL9	TESEL8	*)
85	TE Output line1	W/R	1.2	TESEL 7	TESEL 6	TESEL 5	TESEL 4	TESEL 3	TESEL 2	TESEL1	TESEL 0	2
E4	Power saving 1	W/R					EQ_S	S1[7:0]				+:
E5	Power saving 2	W/R					EQ_S	52[7:0]				+
E6	Power saving 3	W/R	+				EQ_S	S3[7:0]				+
E7	Power saving 4	W/R					EQ S	54[7:0]				
E8	Source OP control_Normal	W/R	. 1680		OPON_N[7:0]					*		
E9	Source OP control IDLE	W/R			OPON_![7:0]							
EA	Power control internal use (1)	W/R	252		STBA[15:8]				<b>5</b> 2			
EB	Power control internal use (2)	W/R	16		STBA[7:0]				12			
EC	Source control internal use (1)	W/R	-		PTBA[15:8]				÷			
ED	Source control internal use (2)	W/R	1.1(2)		PTBA[7:0]			- 20				
FF	Page select	W/R	2.	-				-		PAGE_SE	L[1:0] (00)	÷

**10. AC Characteristics** Parallel interface characteristics (8080-series MPU)



(VSSA=0V, IOVCC=1.65V to 3.3V, VCI=2.3V to 3.3V, T<sub>A</sub> = -30 to 70° C)

Signal	Symbol	Parameter		Spec.			Description	
orginal	Symbol	Faidheter	Min.	Тур	Max.			
DNC_SCL	tAST	Address setup time Address hold time (Write/Read)	10 10	1	1	ns		
NCS	tCS tRCS tRCSFM tCSF tCSH	Chip select "H" pulse width Chip select setup time (Write) Chip select setup time (Read ID) Chip select setup time (Read FM) Chip select wait time (Write/Read) Chip select hold time	0 15 45 355 10 10	0.00		ns	÷	
NWR_SCL	tWC tWC tWRH tWRL	Write cycle( 1pixel for one write) Write cycle (1 pixel for 2 or 3 write) Control pulse "H" duration Control pulse "L" duration	100 50 15 15		.<	ns	*	
NRD(ID)	tRC tRDH tRDL	Read cycle (ID) Control pulse "H" duration (ID) Control pulse "L" duration (ID)	160 90 45	22.	R.C.	ns	When read ID data	
NRD(FM)	tRCFM tRCFM tRDHFM tRDLFM	Read cycle (FM) ( 1pixel for one read) Read cycle (FM) (1 pixel for 2 or 3 read) Control pulse "H" duration (FM) Control pulse "L" duration (FM)	600 400 90 355	S	1	ns	When read from frame memory	
DB17 to DB0	tDST tDHT tRAT tRATFM tODH	Data setup time Data hold time Read access time (ID) Read access time (FM) Output disable time	10	3	100 340 80	ns	For maximum CL=30pF For minimum CL=8pF	

Logic high and low levels an

10% and 70% of IOVCC for Input signals.

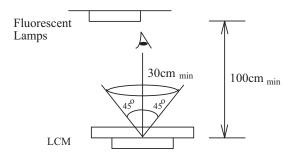
### **<u>11.Quality Specifications</u>**

#### All The raw material are Rohs complicant.

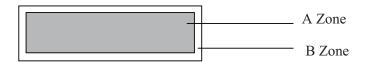
#### 11.1 Standard of the product appearance test

Manner of appearance test: The inspection should be performed in using 20W x 2 fluorescent lamps. Distance between LCM and fluorescent lamps should be 100 cm or more. Distance between LCM and inspector eyes should be 30 cm or more.

Viewing direction for inspection is 45° from vertical against LCM.



Definition of zone:



A Zone: viewing area B Zone: outside viewing area

#### **11.2 Specification of quality assurance**

AQL inspection standard

Sampling method: MIL-STD-105E, Level II, single sampling

Classify		Item	Note	AQL
Major	Display state	Short or open circuit		0.65
		LC leakage		
		Flickering	1	
		No display		
		Wrong viewing direction		
		Contrast defect (dim, ghost)	2	
		Back-light	1,8	
	Non-display	Flat cable or pin reverse	10	
		Wrong or missing component	11	
Minor	Display state	Background color deviation	2	1.0
		Black spot and dust	3	
		Line defect, Scratch	4	
		Rainbow	5	
		Chip	6	
		Pin hole	7	
	Polarizer	Protruded	12	
		Bubble and foreign material	3	]
	Soldering	Poor connection	9	]
	Wire	Poor connection	10	]
	TAB	Position, Bonding strength	13	1

Defect classification (Note: \* is not including)

### Note on defect classification

No.	Item				Criterion	
1	Short or open circuit	Not allow				
	LC leakage					
	Flickering					
	No display					
	Wrong viewing direction					
	Wrong Back-light					
2	Contrast defect		Refe	er to	o approval san	nple
	Background color deviation					
3	Point defect, Black spot, dust	Ŷ			Point Size	Acceptable Qty.
	(including Polarizer)	'X'		0	<u>φ≤</u> 0.10 .10<φ≤0.20	Disregard 3
					.10<φ≪0.20 .20<φ≪0.25	2
	$\phi = (X+Y)/2$				.25<¢≤0.30	1
					φ>0.30	0
			Un	it:	mm	
4	Line defect,					
	Scratch	│ <b>《</b> ↑ <b>**</b>			Line	Acceptable Qty.
					W 0.015≥W	Disregard
			3.0≥	≥L	0.03≥W	2
			2.0≥		0.05≥W	
			1.0≥	≥L	0.1>W 0.05 <w< td=""><td>1 Applied as point defect</td></w<>	1 Applied as point defect
			μ	I I.a.		
		Unit: mm				
5	Rainbow	Not more than two color changes across the viewing area.				

No	Item	Criterion
6	Chip Remark: X: Length direction Y: Short	X $X$ $X$ $X$ $Y$ $Z$ $X$ $Y$ $Z$ $X$ $Y$ $Z$ $X$ $X$ $Y$ $Z$
	direction Z: Thickness direction t: Glass thickness W: Terminal Width	$\begin{array}{c c} X & Y \\ \hline & X & Y \\ \hline & & \\ \hline & & \\ Z \end{array}$ Acceptable criterion $\begin{array}{c c} X & Y & Z \\ \hline & \leq 2 & 0.5 \text{mm} & \leq t \end{array}$
		$Y \xrightarrow{\bigvee} \bigvee_{\leftarrow} X$ Acceptable criterion $X  Y  Z$ $\leq 3  \leq 2  \leq t$ shall not reach to ITO
		$W_{\underline{y}} \xrightarrow{Y} \psi$ Acceptable criterion $X  Y  Z$ $S  S  S  S  S  S  S  S  S  S $
		$\begin{array}{c c} & Y \\ & & \\ \hline \\ & & \\ & \\ & \\ & \\ & \\ & \\ &$

No.	Item	Criterion					
7	Segment pattern W = Segment width $\phi = (X+Y)/2$	(1) Pin hole $\phi < 0.10$ mm is acceptable. X Y Point Size Acceptable Qty $\phi \le 1/4$ W Disregard					
		$\begin{array}{c c} & & & & & \\ \hline & & & & \\ \hline & & & & \\ \hline & & & &$					
8	Back-light	(1) The color of backlight should correspond its specification.					
9	Soldering	<ul> <li>(2) Not allow flickering</li> <li>(1) Not allow heavy dirty and solder ball on PCB.</li> <li>(The size of dirty refer to point and dust defect)</li> <li>(2) Over 50% of lead should be soldered on Land.</li> </ul>					
		Lead					
		50% lead					
10	Wire	<ul> <li>(1) Copper wire should not be rusted</li> <li>(2) Not allow crack on copper wire connection.</li> <li>(3) Not allow reversing the position of the flat cable.</li> <li>(4) Not allow exposed copper wire inside the flat cable.</li> </ul>					
11*	PCB	<ul> <li>(1) Not allow screw rust or damage.</li> <li>(2) Not allow missing or wrong putting of component.</li> </ul>					

	o N m e	t I noiretir C
12	Protruded W: Terminal Width	$W_{\underline{N}}$ $W_{\underline{N}$ $W_{\underline{N}}$ $W_{\underline{N}}$ $W_{\underline{N}}$ $W_{\underline{N}}$ $W_{$
13	TAB	1. Position $H \xrightarrow{W} W1$ ITO $W1 \le 1/3W$ $H1 \le 1/3H$
		2 FPC bonding strength test FFC FPC P (=F/FPC bonding width) ≥650gf/cm ,(speed rate: 1mm/min) 5pcs per SOA (shipment)
14	Total no. of acceptable Defect	<ul> <li>A. Zone</li> <li>Maximum 2 minor non-conformities per one unit.</li> <li>Defect distance: each point to be separated over 10mm</li> <li>B. Zone</li> <li>It is acceptable when it is no trouble for quality and assembly in customer's end product.</li> </ul>

### **11.3 Reliability of LCM**

Reliability test condition:

Item	Condition	Time (hrs)	Assessment
High temp. Storage	60 °C	48	
High temp. Operating	50 °C	48	
Low temp. Storage	-20 °C	48	No abnormalities
Low temp. Operating	-10°C	48	in functions
Humidity	40 °C/ 90%RH	48	and appearance
Temp. Cycle	$-20^{\circ}C \leftarrow 25^{\circ}C \rightarrow 80^{\circ}C$	10cycles	
	$(60 \min \leftarrow 5 \min \rightarrow 60 \min)$		

Recovery time should be 24 hours minimum. Moreover, functions, performance and appearance shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ( $20\pm8$  °C), normal humidity (below 65% RH), and in the area not exposed to direct sun light.

### **11.4 Precaution for using LCD/LCM**

LCD/LCM is assembled and adjusted with a high degree of precision. Do not attempt to make any alteration or modification. The followings should be noted.

#### **General Precautions:**

- 1. LCD panel is made of glass. Avoid excessive mechanical shock or applying strong pressure onto the surface of display area.
- 2. The polarizer used on the display surface is easily scratched and damaged. Extreme care should be taken when handling. To clean dust or dirt off the display surface, wipe gently with cotton, or other soft material soaked with isoproply alcohol, ethyl alcohol or trichlorotriflorothane, do not use water, ketone or aromatics and never scrub hard.
- 3. Do not tamper in any way with the tabs on the metal frame.
- 4. Do not made any modification on the PCB without consulting Orient Display.
- 5. When mounting a LCM, make sure that the PCB is not under any stress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
- 6. Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels and also cause rainbow on the display.
- 7. Be careful not to touch or swallow liquid crystal that might leak from a damaged cell. Any liquid crystal adheres to skin or clothes, wash it off immediately with soap and water.

#### **Static Electricity Precautions:**

- 1. CMOS-LSI is used for the module circuit; therefore operators should be grounded whenever he/she comes into contact with the module.
- 2. Do not touch any of the conductive parts such as the LSI pads; the copper leads on the PCB and the interface terminals with any parts of the human body.
- 3. Do not touch the connection terminals of the display with bare hand; it will cause disconnection or defective insulation of terminals.
- 4. The modules should be kept in anti-static bags or other containers resistant to static for storage.
- 5. Only properly grounded soldering irons should be used.
- 6. If an electric screwdriver is used, it should be grounded and shielded to prevent sparks.
- 7. The normal static prevention measures should be observed for work clothes and working benches.
- 8. Since dry air is inductive to static, a relative humidity of 50-60% is recommended.

#### **Soldering Precautions:**

- 1. Soldering should be performed only on the I/O terminals.
- 2. Use soldering irons with proper grounding and no leakage.
- 3. Soldering temperature:  $280^{\circ}C \pm 10^{\circ}C$
- 4. Soldering time: 3 to 4 second.
- 5. Use eutectic solder with resin flux filling.
- 6. If flux is used, the LCD surface should be protected to avoid spattering flux.
- 7. Flux residue should be removed.

#### **Operation Precautions:**

- 1. The viewing angle can be adjusted by varying the LCD driving voltage Vo.
- 2. Since applied DC voltage causes electro-chemical reactions, which deteriorate the display, the applied pulse waveform should be a symmetric waveform such that no DC component remains. Be sure to use the specified operating voltage.
- 3. Driving voltage should be kept within specified range; excess voltage will shorten display life.
- 4. Response time increases with decrease in temperature.
- 5. Display color may be affected at temperatures above its operational range.
- 6. Keep the temperature within the specified range usage and storage. Excessive temperature and humidity could cause polarization degradation, polarizer peel-off or generate bubbles.
- 7. For long-term storage over 40°C is required, the relative humidity should be kept below 60%, and avoid direct sunlight.

#### **Limited Warranty**

Orient Display's LCDs and modules are not consumer products, but may be incorporated by Orient Display's customers into consumer products or components thereof, Orient Display does not warrant that its LCDs and components are fit for any such particular purpose.

- 1. The liability of Orient Display is limited to repair or replacement on the terms set forth below. Orient Display will not be responsible for any subsequent or consequential events or injury or damage to any personnel or user including third party personnel and/or user. Unless otherwise agreed in writing between Orient Display and the customer, Orient Display will only replace or repair any of its LCD which is found defective electrically or visually when inspected in accordance with Orient Display general LCD inspection standard. (Copies available on request)
- 2. No warranty can be granted if any of the precautions state in handling liquid crystal display above has been disregarded. Broken glass, scratches on polarizer mechanical damages as well as defects that are caused accelerated environment tests are excluded from warranty.
- 3. In returning the LCD/LCM, they must be properly packaged; there should be detailed description of the failures or defect.